

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Amended) Method for soldering an object comprising several soldered joints, which method comprises the steps of:

- mechanically soldering of at least some of the soldered joints;
- visually assessing the soldered joints; and
- correctively soldering the visually assessed soldered joints that do not meet ~~the~~ relevant quality requirements; wherein the corrective soldering is carried out with a selective soldering device,

~~characterized in that~~wherein said visual assessment takes place by means of a video camera and a computing device connected to the video camera, wherein ~~in which computing device~~ the assessment criteria for the soldered joints are stored in the computing device.

2. (Amended) Method according to claim 1, ~~characterized in that~~ wherein said corrective soldering of the soldered joints that do not meet the requirements takes place automatically under the control of the computing device.

3. (Amended) Method according to claim 1 ~~or 2~~, ~~characterized in that~~ wherein said corrective soldering of the soldered joints is carried out with the same soldering ~~means~~ device as said mechanical soldering.

4. (Canceled)

5. (Amended) Method according to ~~any one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said transport takes place by means of a robot.

6. (Amended) Method according to ~~any one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said apparatus is suitable for soldering printed circuit boards.

7. (Amended) Apparatus for soldering objects comprising several soldered joints, which apparatus comprises:

- a conveyor for supplying the objects to be soldered and discharging the soldered objects;
- a mechanical soldering device for soldering the objects to be soldered, characterized by a video camera for recording at least one image of at least some of the soldered joints made by the soldering device;
- a computing device connected to the video camera for receiving from the video camera signals representing images recorded by the video camera, said computing device being arranged for comparing said signals with signals that are representative of correct soldered joints; and
- a corrective soldering device for the corrective soldering of soldered joints that have been found not to meet the criteria that are stored in the computing device; wherein the corrective soldering device is a selective soldering device.

8. (Canceled)

9. (Amended) Apparatus according to claim 7 ~~or 8~~, characterized ~~in that~~ wherein said corrective soldering device is arranged for the corrective soldering of only those soldered joints that have been found not to meet the ~~relevant~~ criteria.

10. (Canceled)

11. (Amended) Apparatus according to ~~any one of the claims 7-10~~ claim 7, characterized ~~in that the apparatus comprises~~ further comprising a handling device for carrying out the following operations under the control of the computing device:

- moving the objects to be soldered from the conveyor to the soldering device;
- moving the soldered objects from the soldering device to a position within the recording area of the video camera;
- moving the soldered objects from the recording area of the video camera to the

conveyor; and

- moving the soldered objects from the video camera to and from the corrective soldering device, ~~and vice versa~~, if the ~~recorded image~~ recorded by the video camera does not meet the criteria that are stored in the computing device ~~gives cause for this~~.

12. (Amended) Apparatus according to claim 11, ~~characterized in that~~wherein said handling device is ~~made up of a robot, which is controlled by the computing device~~.

13. (Amended) Apparatus according to ~~any one of the claims 7-12~~claim 7, ~~characterized in that~~wherein the apparatus is suitable for handling printed circuit boards.

14. (Amended) Apparatus according to ~~any one of the claims 7-13~~claim 7, ~~characterized in that~~wherein said corrective soldering device is arranged for soldering only a single soldered joint or a single group of soldered joints under the control of the computing device.

15. (Canceled)

16. (Amended) Apparatus according to claim ~~15~~14, ~~characterized in that~~wherein said handling device is suitable for exchanging masking plates under the control of the computing device.

17. (New) Method according to claim 1, wherein said corrective soldering of the soldered joints is carried out with a different soldering device as said mechanical soldering.

18. (New) Method of claim 17, wherein the mechanical soldering is carried out with a wave soldering device.

19. (New) Apparatus according to claim 7, wherein said mechanical soldering device is a selective soldering device.

20. (New) Apparatus according to claim 19, wherein said mechanical soldering device and said corrective soldering device are the same device.

21. (New) Apparatus according to claim 7, wherein the mechanical soldering device is a wave soldering device.